

PATENT  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yoshihiro BASHO et al.

Serial No: Not assigned

Filed: January 15, 2004

For: Heat Releasing Member, Package for Accommodating  
Semiconductor Element and Semiconductor Device

Art Unit: Not assigned

Examiner: Not assigned

**TRANSMITTAL OF INFORMATION DISCLOSURE  
STATEMENT**

Mail Stop PATENT APPLICATION  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

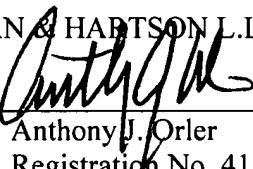
Dear Sir:

The information disclosure statement submitted herewith is being filed concurrently with the subject application [37 C.F.R. § 1.97(b)] and contains no items of information cited in any communication from a foreign patent office in a counterpart foreign application [37 C.F.R. § 1.97(e)(1)].

If it should be determined that for any reason either an insufficient or excessive fee has been paid, please charge any insufficiency or credit any overpayment necessary to ensure consideration of the information disclosure statement for the above-identified application to Deposit Account No. 50-1314. A copy of this paper is enclosed.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

By: 

Anthony J. Orler  
Registration No. 41,232  
Attorney for Applicant(s)

Date: January 15, 2004

500 South Grand Avenue, Suite 1900  
Los Angeles, California 90071  
Telephone: 213-337-6700  
Facsimile: 213-337-6701

